

## REMARKS/ARGUMENTS

The applicant's attorneys appreciate the Examiner's comments.

Claim 1 and claim 38 have been rejected as obvious over Muessli in view of Mies et al. (Mies). Reconsideration is requested.

Muessli and Mies both disclose a device in which the circuit board is vertically oriented such that its component receiving surfaces face the wall of the screw base. As a result of such an arrangement, the maximum area for receiving components can be obtained if the circuit board is aligned with the center vertical plane of the screw base. To attain maximum area for receiving components, however, would limit the height of the components to one half of the diameter of the circular base of the screw base. To accommodate components having a higher height the circuit board must be spaced from the center plane, which would result in the reduction of the available area for receiving components.

Furthermore, Muessli teaches supporting its circuit board 41 inside the screw base using inner lid 60. See col. 5, lines 20-29. Mies, on the other hand, only states that the "heat-conducting plate P is fastened in the space 7 by means not shown in Fig. 1". Page 3, line 29. There is no disclosure that body D can support heat conducting plate in that: a) it is not clear that body D can adhere to housing 6 and plate P well enough to support plate P in the manner shown in Fig. 1 (i.e. suspended inside space 7 above the bottom of the screw base); b) body D is a paste, which due to its relative compliability, would not be expected to resist sagging when attached to plate P as shown in Fig. 1. With respect to the latter, it should be noted that body D is made from Eccoetherm TC-4. As disclosed in the attached data sheet, Eccoetherm TC-4 is a liquid/paste. Thus, it would not be reasonable to expect that body D as disclosed by Mies would have the inherent capability to support plate P in the manner shown.

On the other hand, in a CFLP according to claim 1 or claim 38, the circuit board is arranged such that its component receiving surfaces are facing the opening and the bottom of the screw base. As a result of such an arrangement, the lower height components can be received on

one surface, and the higher height components on the other surface, whereby nearly all of the depth of the screw base can be made available without a need to vary the component receiving area of the circuit board.

Furthermore, claims 1 and 38 now call for the thermally conductive body to support the circuit board inside the screw base. Neither Mies, nor Muessli teaches or suggests using a thermally conductive body to both transmit heat to the screw base for dissipation and to support the ballast module inside the screw base. For these reasons, claims 1 and 38 should be deemed allowable over the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

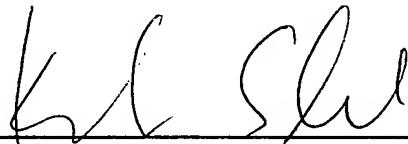
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March 28, 2006  
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KS:gl

Respectfully submitted,



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**Alternate Vendors**

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**SECTION III - Physical/Chemical Characteristics**

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Appearance/Odor	<u>OFF-WHITE LIQUID/PASTE</u>
Boiling Point	N/K
Melting Point	N/K
Vapor Pressure	NEGLIG
Vapor Density	N/K
Specific Gravity	2.2
Decomposition Temperature	UNKNOWN
Evaporation Rate	N/K
Solubility in Water	INSOLUBLE
Percent Volatiles by Volume	NEGLI
Chemical pH	N/R
Corrosion Rate	UNKNOWN
Container Pressure Code	4
Temperature Code	8
Product State Code	L

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**SECTION IV - Fire and Explosion Hazard Data**

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Flash Point Method	UNK
Lower Explosion Limit	N/R
Upper Explosion Limit	N/R
Extinguishing Media	USE WATER FOG, CARBON DIOXIDE, FOAM, OR DRY CHEMICAL
Special Fire Fighting Procedures	WEAR FIRE FIGHTING PROTECTIVE EQUIPMENT AND A FULL FACED SELF CONTAINED BREATHING APPARATUS. COOL FIRE EXPOSED CONTAINERS WITH WATER SPRAY
Unusual Fire/Explosion Hazards	COMBUSTION OR HEAT OF FIRE MAY PRODUCE HAZARDOUS DECOMPOSITION PRODUCTS AND VAPORS. CONTAINERS MAY RUPTURE UNDER FIRE CONDITIONS

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**SECTION V - Reactivity Data**

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Stability	YES
Stability Conditions to Avoid	HIGH HEAT, OPEN FLAMES, AND OTHER SOURCES OF IGNITION. AVOID STORAGE IN OPEN CONTAINERS

Materials to Avoid	STRONG OXIDIZING AGENTS, ACIDS AND BASES
Hazardous Decomposition Products	COMBUSTION WILL PRODUCE SILICON DIOXIDE
Hazardous Polymerization	NO
Polymerization Conditions to Avoid	N/A

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## SECTION VI - Health Hazard Data

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Route of Entry: Skin	YES
Route of Entry: Ingestion	NO
Route of Entry: Inhalation	NO
Health Hazards - Acute and Chronic	EYE:IRRITATION.SKIN:SLIGHT IRRITATION:INHALATION:VAPORS MAY CAUSE RESPIRATORY IRRITATION, UNLIKELY AT ROOM TEMP.INGESTION:HARMFUL IF SWALLOWED.CHRONIC EXPOSURE UNLIKELY UNLESS THE PRODUCT IS APPLIED IN A MANNER WHICH RESULTS IN MISTS OR FUMES
Symptoms of Overexposure	EYE:BLURRED VISION,BURNING SENSATION AND TEARING
Medical Cond. Aggravated by Exposure	NO DATA IS AVAILABLE FOR THIS PRODUCT MIXTURE
Emergency/First Aid Procedures	EYE:FLUSH W/WATER 15MIN WHILE HOLDING EYELIDS OPEN.SEE DR. SKIN:WASH W/SOAP/WATER. IF IRRITATION PERSISTS,SEE DR. INHALATION:REMOVE TO FRESH AIR,SEE DR. INGESTION:DILUTE BY GIVING PLENTY OF WATER TO DRINK

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## SECTION VII - Precautions for Safe Handling and Use

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Steps if Material Released/Spilled	SMALL SPILLS:ACTIVATE EXHAUST VENTILATION.WIPE UP OR ABSORB SPILLED MATERIAL W/VERMICULITE OR OTHER SIMILAR MATERIAL.WASH AREA W/SOAPY MATERIAL.LARGE SPILLS:SHUT OFF RELEASE IF POSSIBLE.DIKE AREA TO CONTAIN SPILL. CLEAN AREA
Neutralizing Agent	NONE
Waste Disposal Method	DISPOSE OF IN AN APPROPRIATE DISPOSAL FACILITY I/A/W FEDERAL, STATE, LOCAL REGULATIONS
Handling and Storage Precautions	STORE IN A COOL, DRY PLACE W/ADEQUATE VENTILATION.KEEP CONTAINERS TIGHTLY CLOSED WHEN NOT IN USE.KEEP AWAY FROM



CAS Number	1314132
Proprietary	NO
Percent	80
OSHA PEL	15MG/M3
ACGIH TLV	10MG/M3
Recommended Limit	NONE
Ingredient #	02
Ingredient Name	SILICONE RESIN
CAS Number	1003
Proprietary	NO
Percent	30

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